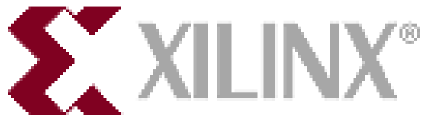

100% Material Declaration Data Sheet FGG860

Average Weight: 10.904 g

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
Silicon Die					**0.1201**	**1.10%**
	Silicon	7440-21-3	100.00		0.1201	
Die Attach Material					**0.012**	**0.11%**
	Silver	7440-22-4	75.00		0.009	
	Resin	Trade Secret	25.00		0.003	
Mold Compound					**0.4135**	**7.31%**
	Epoxy Resins	Trade Secret	26.00		0.207	
	SiO2	60676-86-0	74.00	Filler	0.590	
Laminate					**0.7897**	**7.24%**
	Laminate	Trade Secret			0.481	
	Solder Mask	Trade Secret			0.168	
	Copper	7440-50-8		Metal Layer	0.122	
	Nickel	7440-02-0		Metal Layer	0.014	
	Gold	7440-57-5		Metal Layer	0.005	
Heat Sink					**7.0645**	**64.79%**
	Copper	7440-50-8	97.50		6.888	
	Iron	7439-89-6	2.35		0.166	
	Phosphorus	7723-14-0	0.003		0.0002	
	Zinc	7440-66-6	0.12		0.008	
Heat Snk Plating					**0.3292**	**3.02%**
	Nickel	7440-05-0	100.00		0.3292	
Dam					**0.0148**	**0.13%**
	Epoxy Resin	Trade Secret	100.00		0.0.148	
Bond Wire					**0.0236**	**0.22%**
	Gold	7440-57-5	100.00		0.0236	
Solder Balls					**1.752**	**16.07%**
	Tin	7440-31-5	95.50		1.67316	
	Silver	7440-22-4	4.00		0.07008	
	Copper	7440-50-8	0.50		0.00876	

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Xilinx believes this environmental information to be correct, but cannot guarantee its completeness or accuracy as it is based on data received from sources outside our company.

Revision History

The following table shows the revision history for this document.

Date	Revision	Revision
3/27/06	1.0	Initial release.
5/15/06	1.1	100% Material Declaration.
9/22/06	1.2	Updated component descriptions.